

Pro-Tech Interconnect Solutions QML Listing

MIL-PRF-31032

Attribute	GI Material	GF Material
Max. Number of Layers	10	16
Max. Panel Size	18" X 24"	18" X 24"
Max. Board Thickness	0.100"	.100"
Min. Drilled PTH (before plating)	0.024"	.0059"
Min. Laser Ablated Plated Hole (before plating)	N/A	.005"
Aspect Ratio (pth)	4:1	15:1
Aspect Ratio (microvia)	N/A	1:1
Blind Vias		Yes
Buried Vias		Yes
Min. Conductor Width	0.005"	.003"
Min. Conductor Space	0.005"	.002"
Hole Preparation	<i>Permanganate Desmear</i>	<i>Permanganate Desmear</i>
	<i>Plasma Etchback</i>	<i>Plasma Etchback</i>
Hole Wall Conductive Coating	<i>Direct Metallization</i>	<i>Direct Metallization</i>
Copper Plating	<i>Direct Current Plate</i>	<i>Direct Current Plate</i>
Hole Fill / Via Plug	N/A	Conductive / Non-Conductive
Solder Resist	<i>Liquid Photoimageable</i>	<i>Liquid Photoimageable</i>
Finish System		<i>Electrolytic Ni/Hard Au</i>
		<i>ENIG</i>
		<i>ImmAg</i>
		<i>OSP</i>
	<i>HASL</i>	HASL
Additional Fab Capabilities		Phase Lamination
Controlled Impedance	N/A	Single Ended
	N/A	Differential
Material	GI	GF